

### AMENDMENTS TO THE CLAIMS

Please amend the Claim Form and Claim as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (currently amended): A conductive resin film constituted by laminated layers comprising:

a conductive substrate layer; and

a low-resistance layer with a volume resistance of 0.1 to 1.0  $\Omega\text{cm}$  in a thickness direction as at least one of its outermost layer;

each layer of the laminated layers being made of a thermoplastic resin and a conductive agent,

wherein the substrate layer comprises a conductive agent selected from the group consisting of graphite powder, exfoliated graphite, carbon black, carbon fiber, carbon nanofiber, carbon nanotube, a metal carbide, a metal nitride, a metal oxide, metal fiber and metal powder;

wherein the conductive substrate layer and the low-resistance layer comprise a thermoplastic resin selected from the group consisting of polyolefin resins, polyolefin elastomers, amorphous polyolefin resins, polystyrene resins, hydrogenated styrene elastomers, polyvinyl chloride resins, polyvinylidene chloride resins, (meth)acrylate, (meth)acrylic resins, polyetherimide resins, polysulphone resins, polyethersulphone resin, polyamide imide resins, polyallylate resins, fluororesins and fluoro-elastomers; and

wherein a volume resistance of the low-resistance layer in a thickness direction is 1/5 or less of a volume resistance of the substrate layer in a thickness direction.

2 (canceled):

3 (previously presented): The conductive resin film as claimed in Claim 1, wherein the low-resistance layer is a layer in which the thermoplastic resin comprises a fine carbon fiber with a fiber diameter of 0.003 to 0.5  $\mu\text{m}$  and a fiber length of 0.1 to 100  $\mu\text{m}$  as a conductive agent.

4 (previously presented): The conductive resin film as claimed in Claim 1, wherein a thickness of the low-resistance layer is 1 to 50  $\mu\text{m}$ .

5 (canceled)

6 (previously presented): A process for manufacturing a conductive resin film as claimed in Claim 1, comprising the steps of applying a liquid composition of a fine carbon fiber and a thermoplastic resin in a solvent to a flat surface of a support, followed by drying or curing to form a coating film; placing the coating film over at least one side of a conductive substrate layer made of a thermoplastic resin and a conductive agent; and performing a lamination.

7 (previously presented): A conductive resin film as claimed in Claim 1 used as a collector for an electric double layer capacitor.

8 (original): A collector for an electric double layer capacitor comprising the conductive resin film as claimed in Claim 7.

9-23 (canceled)

24 (new): The conductive resin film as claimed in Claim 1, wherein the thermoplastic resin is selected from the group consisting of polyolefin resins, polyolefin elastomers, hydrogenated styrene elastomers, fluororesins and fluoro-elastomers.

25 (new): The conductive resin film as claimed in Claim 24, wherein the thermoplastic resin from fluororesins or fluoro-elastomers is selected from the group consisting of polytetrafluoroethylene, tetrafluoroethylene-perfluoroalkyl vinyl ether copolymer, tetrafluoroethylene-hexafluoropropylene copolymer, tetrafluoroethylene-hexafluoropropylene perfluoroalkyl vinyl ether copolymer, tetrafluoroethylene-ethylene copolymer, polychlorotrifluoroethylene, chlorotrifluoroethylene-ethylene copolymer, polyvinylidene fluoride, polyvinyl fluoride, tetrafluoroethylene-hexafluoropropylene-vinylidene fluoride copolymer, vinylidene fluoride-hexafluoropropylene copolymer, vinylidene fluoride-propylene copolymer, fluorine-containing silicone rubbers, fluorine-containing vinyl ether rubbers, fluorine-containing phosphazene rubbers and fluorine-containing thermoplastic elastomers; and/or

wherein the thermoplastic resin from polyolefin resins or polyolefin elastomers is selected from the group consisting of polyethylene, polypropylene, polybutene, poly(4-methyl-1-pentene), polyhexene, polyoctene, hydrogenated styrene-butadiene rubbers, EPDM, EPM and EBM.

26 (new): The conductive resin film as claimed in Claim 1, wherein the thermoplastic resin is selected from the group consisting of polyvinylidene fluoride, tetrafluoroethylene-hexafluoropropylene-vinylidene fluoride copolymer, vinylidene fluoride-

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hexafluoropropylene, copolymer, vinylidene fluoride-propylene copolymer, polyethylene, polypropylene, EPDM and hydrogenated styrene-butadiene rubbers.

27 (new): The conductive resin film as claimed in Claim 1, wherein a volume resistance of the conductive resin film as a hole in a thickness direction is 0.01 to 5  $\Omega\text{cm}$ .